

REV.	ECN NO	LOCATIONS	DESCRIPTION	DATE

A

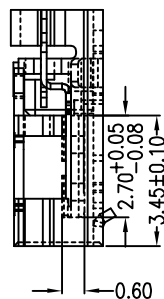
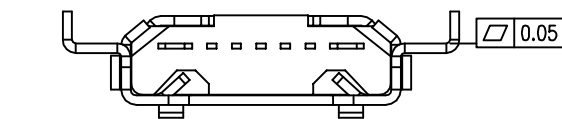
B

C

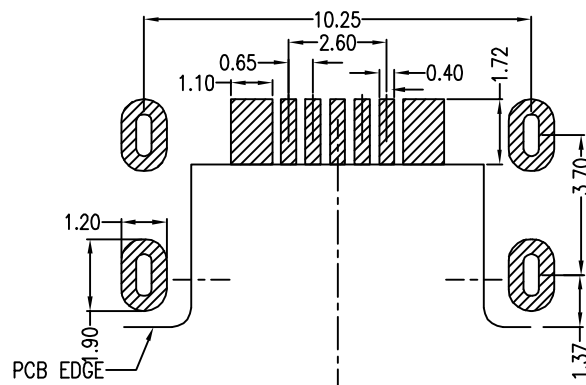
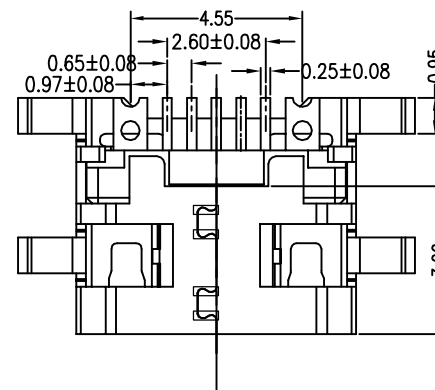
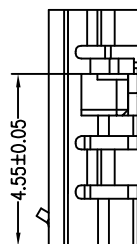
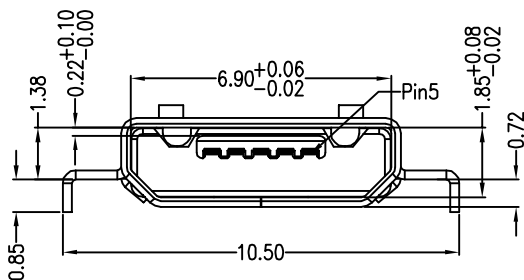
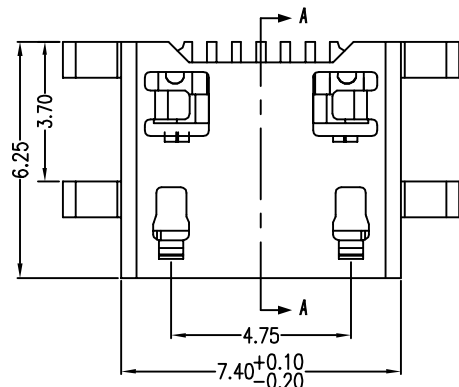
D

E

F



SEC A-A



RECOMMENDED PCB LAYOUT

Note:

1.Material:

- 1.1 Housing: High temperature thermoplastic with g.f,UL94v-0
- 1.2 Contact: copper alloy,t=0.15mm
- 1.3 Shell: copper alloy,t=0.25mm

2.Specification:

- 2.1 Current rating: 1 A Max.
- 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
- 2.3 Contact resistance: 50 mW Max.
- 2.4 Insulation resistance: 100 MW Min.
- 2.5 Total mating force: 3.57 Kg Max.
- 2.6 Total unmating force: 1.0 Kg Min.0.81~2.05 Kg Min.after 10000 insertion/extraction cycles
- 2.7 Temperature range: -30°C~80°C

A 01 S B X X X X X X X 3-165

① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪ ⑫ ⑬

- ① 产品代号 A:成品
- ② 产品系列 01:micro usb 5pin
- ③ 产品类别 S:母座
- ④ 产品类型 B:B TYPE
- ⑤ 外壳材质 1:C2680R-H
- ⑥ 外壳电镀 0:素材;1: Ni100u'';2:雾Sn100u'';3:Ni+Au1u''(圆);4:金Au1u''
- ⑦ 端子材质 4:05191R-EH 2:C2680R-EH
- ⑧ 端子电镀 0:素材;1:金Au1u'';2:金Au1.5u'';3:金Au10u'';4:金Au10u'';5:金Au10u'';6:金Au10u'';7:雾Sn+Au1u'';8:雾Sn+Au1u'';9:雾Sn+Au1u'';10:雾Sn+Au1u'';11:雾Sn+Au1u'';12:雾Sn+Au1u'';13:雾Sn+Au1u''
- ⑨ 主体材质 1:LCP
- ⑩ 主体颜色 B:黑色 W:白色
- ⑪ 包装方式 1:吸塑管;2:卷带;4:pe袋
- ⑫ 下板类型 3:沉板式
- ⑬ 细节流水 165:Micro usb 5s B Type Smt(沉板式)无导位

PART NO: AO1SBXXXXXX3-165	MATERIAL: SEE NOTE	TITLE: Micro usb 5s B Type Smt(沉板式)无导位	
MODEL NO: XX	FINISH: SEE NOTE		
UNIT: MM	SIZE: A4	DWG NO: A165	
TOLERANCE UNSPECIFIED .x 0.25 .xx 0.20 .xxx 0.15 Ang. 2°		DR: 夏友红	REV: A
		CHK:	
		APP:	
		SCALE: 5:1	DATE: 2012.06.18